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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	C166SV2
Core Size	16-Bit
Speed	66MHz
Connectivity	CANbus, EBI/EMI, I ² C, LINbus, SPI, SSC, UART/USART, USI
Peripherals	I ² S, POR, PWM, WDT
Number of I/O	118
Program Memory Size	576KB (576K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	50K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 24x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-144-4
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xe167f72f66lacfxqma1

Summary of Features

Table 1 XE167 Derivative Synopsis

Derivative¹⁾	Temp. Range	Program Memory²⁾	PSRAM³⁾	CCU6 Mod.	ADC⁴⁾ Chan.	Interfaces⁴⁾
SAF-XE167F-48F66L	-40 °C to 85 °C	384 Kbytes Flash	16 Kbytes	0, 1, 2, 3	16 + 8	5 CAN Nodes, 6 Serial Chan.
SAF-XE167F-72F66L	-40 °C to 85 °C	576 Kbytes Flash	32 Kbytes	0, 1, 2, 3	16 + 8	5 CAN Nodes, 6 Serial Chan.
SAF-XE167F-96FxxL	-40 °C to 85 °C	768 Kbytes Flash	64 Kbytes	0, 1, 2, 3	16 + 8	5 CAN Nodes, 6 Serial Chan.
SAF-XE167G-48F66L	-40 °C to 85 °C	384 Kbytes Flash	16 Kbytes	0, 1	8 + 8	2 CAN Nodes, 4 Serial Chan.
SAF-XE167G-72F66L	-40 °C to 85 °C	576 Kbytes Flash	32 Kbytes	0, 1	8 + 8	2 CAN Nodes, 4 Serial Chan.
SAF-XE167G-96F66L	-40 °C to 85 °C	768 Kbytes Flash	64 Kbytes	0, 1	8 + 8	2 CAN Nodes, 4 Serial Chan.
SAF-XE167H-48F66L	-40 °C to 85 °C	384 Kbytes Flash	16 Kbytes	0, 1, 2, 3	16 + 8	No CAN Node, 6 Serial Chan.
SAF-XE167H-72F66L	-40 °C to 85 °C	576 Kbytes Flash	32 Kbytes	0, 1, 2, 3	16 + 8	No CAN Node, 6 Serial Chan.
SAF-XE167H-96F66L	-40 °C to 85 °C	768 Kbytes Flash	64 Kbytes	0, 1, 2, 3	16 + 8	No CAN Node, 6 Serial Chan.
SAF-XE167K-48F66L	-40 °C to 85 °C	384 Kbytes Flash	16 Kbytes	0, 1	8 + 8	No CAN Node, 4 Serial Chan.
SAF-XE167K-72F66L	-40 °C to 85 °C	576 Kbytes Flash	32 Kbytes	0, 1	8 + 8	No CAN Node, 4 Serial Chan.
SAF-XE167K-96F66L	-40 °C to 85 °C	768 Kbytes Flash	64 Kbytes	0, 1	8 + 8	No CAN Node, 4 Serial Chan.

1) This Data Sheet is valid for devices starting with and including design step AC.

2) Specific information about the on-chip Flash memory in [Table 2](#).

3) All derivatives additionally provide 1 Kbyte SBRAM, 2 Kbytes DPRAM, and 16 Kbytes DSRAM.

4) Specific information about the available channels in [Table 3](#).

Analog input channels are listed for each Analog/Digital Converter module separately (ADC0 + ADC1).

Notes to Pin Definitions

1. **Ctrl.:** The output signal for a port pin is selected by bitfield PC in the associated register Px_IOCry. Output O0 is selected by setting the respective bitfield PC to 1x00_B, output O1 is selected by 1x01_B, etc.
Output signal OH is controlled by hardware.
2. **Type:** Indicates the pad type used (St=standard pad, Sp=special pad, DP=double pad, In=input pad, PS=power supply) and its power supply domain (A, B, M, 1).

Table 4 Pin Definitions and Functions

Pin	Symbol	Ctrl.	Type	Function
3	$\overline{\text{TESTM}}$	I	In/B	Testmode Enable Enables factory test modes, must be held HIGH for normal operation (connect to V_{DDPB}). An internal pullup device will hold this pin high when nothing is driving it.
4	P7.2	O0 / I	St/B	Bit 2 of Port 7, General Purpose Input/Output
	EMUX0	O1	St/B	External Analog MUX Control Output 0 (ADC1)
	TxDC4	O2	St/B	CAN Node 4 Transmit Data Output
	CCU62_ CCPOS0A	I	St/B	CCU62 Position Input 0
	TDI_C	I	St/B	JTAG Test Data Input
5	P8.4	O0 / I	St/B	Bit 4 of Port 8, General Purpose Input/Output
	CCU60_ COUT61	O1	St/B	CCU60 Channel 1 Output
	TMS_D	I	St/B	JTAG Test Mode Selection Input
6	$\overline{\text{TRST}}$	I	In/B	Test-System Reset Input For normal system operation, pin $\overline{\text{TRST}}$ should be held low. A high level at this pin at the rising edge of $\overline{\text{PORST}}$ activates the XE167's debug system. In this case, pin $\overline{\text{TRST}}$ must be driven low once to reset the debug system. An internal pulldown device will hold this pin low when nothing is driving it.
7	P8.3	O0 / I	St/B	Bit 3 of Port 8, General Purpose Input/Output
	CCU60_ COUT60	O1	St/B	CCU60 Channel 0 Output
	TDI_D	I	St/B	JTAG Test Data Input

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
79	P0.1	O0 / I	St/B	Bit 1 of Port 0, General Purpose Input/Output
	U1C0_DOUT	O1	St/B	USIC1 Channel 0 Shift Data Output
	TxDC0	O2	St/B	CAN Node 0 Transmit Data Output
	CCU61_ CC61	O3 / I	St/B	CCU61 Channel 1 Input/Output
	A1	OH	St/B	External Bus Interface Address Line 1
	U1C0_DX0B	I	St/B	USIC1 Channel 0 Shift Data Input
	U1C0_DX1A	I	St/B	USIC1 Channel 0 Shift Clock Input
80	P2.8	O0 / I	DP/B	Bit 8 of Port 2, General Purpose Input/Output
	U0C1_ SCLKOUT	O1	DP/B	USIC0 Channel 1 Shift Clock Output
	EXTCLK	O2	DP/B	Programmable Clock Signal Output ¹⁾
	CC2_21	O3 / I	DP/B	CAPCOM2 CC21IO Capture Inp./ Compare Out.
	A21	OH	DP/B	External Bus Interface Address Line 21
	U0C1_DX1D	I	DP/B	USIC0 Channel 1 Shift Clock Input
81	P4.7	O0 / I	St/B	Bit 7 of Port 4, General Purpose Input/Output
	CC2_31	O3 / I	St/B	CAPCOM2 CC31IO Capture Inp./ Compare Out.
	T4EUD	I	St/B	GPT1 Timer T4 External Up/Down Control Input
82	P2.9	O0 / I	St/B	Bit 9 of Port 2, General Purpose Input/Output
	U0C1_DOUT	O1	St/B	USIC0 Channel 1 Shift Data Output
	TxDC1	O2	St/B	CAN Node 1 Transmit Data Output
	CC2_22	O3 / I	St/B	CAPCOM2 CC22IO Capture Inp./ Compare Out.
	A22	OH	St/B	External Bus Interface Address Line 22
	CLKIN1	I	St/B	Clock Signal Input
	TCK_A	I	St/B	JTAG Clock Input

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
92	TRef	IO	Sp/1	Control Pin for Core Voltage Generation 2)
93	P3.2	O0 / I	St/B	Bit 2 of Port 3, General Purpose Input/Output
	U2C0_SCLKOUT	O1	St/B	USIC2 Channel 0 Shift Clock Output
	TxDC3	O2	St/B	CAN Node 3 Transmit Data Output
	U2C0_DX1B	I	St/B	USIC2 Channel 0 Shift Clock Input
	HOLD	I	St/B	External Bus Master Hold Request Input
94	P2.10	O0 / I	St/B	Bit 10 of Port 2, General Purpose Input/Output
	U0C1_DOUT	O1	St/B	USIC0 Channel 1 Shift Data Output
	U0C0_SELO3	O2	St/B	USIC0 Channel 0 Select/Control 3 Output
	CC2_23	O3 / I	St/B	CAPCOM2 CC23IO Capture Inp./ Compare Out.
	A23	OH	St/B	External Bus Interface Address Line 23
	U0C1_DX0E	I	St/B	USIC0 Channel 1 Shift Data Input
	CAPIN	I	St/B	GPT2 Register CAPREL Capture Input
95	P10.3	O0 / I	St/B	Bit 3 of Port 10, General Purpose Input/Output
	CCU60_COUT60	O2	St/B	CCU60 Channel 0 Output
	AD3	OH / I	St/B	External Bus Interface Address/Data Line 3
	U0C0_DX2A	I	St/B	USIC0 Channel 0 Shift Control Input
	U0C1_DX2A	I	St/B	USIC0 Channel 1 Shift Control Input
96	P0.5	O0 / I	St/B	Bit 5 of Port 0, General Purpose Input/Output
	U1C1_SCLKOUT	O1	St/B	USIC1 Channel 1 Shift Clock Output
	U1C0_SELO2	O2	St/B	USIC1 Channel 0 Select/Control 2 Output
	CCU61_COUT62	O3	St/B	CCU61 Channel 2 Output
	A5	OH	St/B	External Bus Interface Address Line 5
	U1C1_DX1A	I	St/B	USIC1 Channel 1 Shift Clock Input
	U1C0_DX1C	I	St/B	USIC1 Channel 0 Shift Clock Input

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
115	P10.9	O0 / I	St/B	Bit 9 of Port 10, General Purpose Input/Output
	U0C0_SELO4	O1	St/B	USIC0 Channel 0 Select/Control 4 Output
	U0C1_MCLKOUT	O2	St/B	USIC0 Channel 1 Master Clock Output
	AD9	OH / I	St/B	External Bus Interface Address/Data Line 9
	CCU60_CCPOS2A	I	St/B	CCU60 Position Input 2
	TCK_B	I	St/B	JTAG Clock Input
116	P1.1	O0 / I	St/B	Bit 1 of Port 1, General Purpose Input/Output
	CCU62_COUT62	O1	St/B	CCU62 Channel 2 Output
	U1C0_SELO5	O2	St/B	USIC1 Channel 0 Select/Control 5 Output
	U2C1_DOUT	O3	St/B	USIC2 Channel 1 Shift Data Output
	A9	OH	St/B	External Bus Interface Address Line 9
	ESR2_3	I	St/B	ESR2 Trigger Input 3
	EX1BINA	I	St/B	External Interrupt Trigger Input
	U2C1_DX0C	I	St/B	USIC2 Channel 1 Shift Data Input
117	P10.10	O0 / I	St/B	Bit 10 of Port 10, General Purpose Input/Output
	U0C0_SELO0	O1	St/B	USIC0 Channel 0 Select/Control 0 Output
	CCU60_COUT63	O2	St/B	CCU60 Channel 3 Output
	AD10	OH / I	St/B	External Bus Interface Address/Data Line 10
	U0C0_DX2C	I	St/B	USIC0 Channel 0 Shift Control Input
	TDI_B	I	St/B	JTAG Test Data Input
	U0C1_DX1A	I	St/B	USIC0 Channel 1 Shift Clock Input

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
118	P10.11	O0 / I	St/B	Bit 11 of Port 10, General Purpose Input/Output
	U1C0_SCLKOUT	O1	St/B	USIC1 Channel 0 Shift Clock Output
	BRKOUT	O2	St/B	OCDS Break Signal Output
	AD11	OH / I	St/B	External Bus Interface Address/Data Line 11
	U1C0_DX1D	I	St/B	USIC1 Channel 0 Shift Clock Input
	RxDC2B	I	St/B	CAN Node 2 Receive Data Input
	TMS_B	I	St/B	JTAG Test Mode Selection Input
119	P9.2	O0 / I	St/B	Bit 2 of Port 9, General Purpose Input/Output
	CCU63_CC62	O1 / I	St/B	CCU63 Channel 2 Input/Output
120	P1.2	O0 / I	St/B	Bit 2 of Port 1, General Purpose Input/Output
	CCU62_CC62	O1 / I	St/B	CCU62 Channel 2 Input/Output
	U1C0_SELO6	O2	St/B	USIC1 Channel 0 Select/Control 6 Output
	U2C1_SCLKOUT	O3	St/B	USIC2 Channel 1 Shift Clock Output
	A10	OH	St/B	External Bus Interface Address Line 10
	ESR1_4	I	St/B	ESR1 Trigger Input 4
	CCU61_T12HRB	I	St/B	External Run Control Input for T12 of CCU61
	EX2AINA	I	St/B	External Interrupt Trigger Input
	U2C1_DX0D	I	St/B	USIC2 Channel 1 Shift Data Input
	U2C1_DX1C	I	St/B	USIC2 Channel 1 Shift Clock Input
121	P10.12	O0 / I	St/B	Bit 12 of Port 10, General Purpose Input/Output
	U1C0_DOUT	O1	St/B	USIC1 Channel 0 Shift Data Output
	TxDC2	O2	St/B	CAN Node 2 Transmit Data Output
	TDO_B	O3	St/B	JTAG Test Data Output
	AD12	OH / I	St/B	External Bus Interface Address/Data Line 12
	U1C0_DX0C	I	St/B	USIC1 Channel 0 Shift Data Input
	U1C0_DX1E	I	St/B	USIC1 Channel 0 Shift Clock Input

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
131	P1.5	O0 / I	St/B	Bit 5 of Port 1, General Purpose Input/Output
	CCU62_ COUT60	O1	St/B	CCU62 Channel 0 Output
	U1C1_ SELO3	O2	St/B	USIC1 Channel 1 Select/Control 3 Output
	BRKOUT	O3	St/B	OCDS Break Signal Output
	A13	OH	St/B	External Bus Interface Address Line 13
	U2C0_DX0C	I	St/B	USIC2 Channel 0 Shift Data Input
132	P9.6	O0 / I	St/B	Bit 6 of Port 9, General Purpose Input/Output
	CCU63_ COUT63	O1	St/B	CCU63 Channel 3 Output
	CCU63_ COUT62	O2	St/B	CCU63 Channel 2 Output
	CCU63_ CTRAPA	I	St/B	CCU63 Emergency Trap Input
	CCU60_ CCPOS1B	I	St/B	CCU60 Position Input 1
133	P1.6	O0 / I	St/B	Bit 6 of Port 1, General Purpose Input/Output
	CCU62_ CC61	O1 / I	St/B	CCU62 Channel 1 Input/Output
	U1C1_ SELO2	O2	St/B	USIC1 Channel 1 Select/Control 2 Output
	U2C0_DOUT	O3	St/B	USIC2 Channel 0 Shift Data Output
	A14	OH	St/B	External Bus Interface Address Line 14
	U2C0_DX0D	I	St/B	USIC2 Channel 0 Shift Data Input
134	P9.7	O0 / I	St/B	Bit 7 of Port 9, General Purpose Input/Output
	CCU63_ CTRAPB	I	St/B	CCU63 Emergency Trap Input
	U2C0_DX1D	I	St/B	USIC2 Channel 0 Shift Clock Input
	CCU60_ CCPOS0B	I	St/B	CCU60 Position Input 0

Functional Description

The XE167 includes an excellent mechanism to identify and process exceptions or error conditions that arise during run-time, the so-called 'Hardware Traps'. A hardware trap causes an immediate non-maskable system reaction similar to a standard interrupt service (branching to a dedicated vector table location). The occurrence of a hardware trap is also indicated by a single bit in the trap flag register (TFR). Unless another higher-priority trap service is in progress, a hardware trap will interrupt any ongoing program execution. In turn, hardware trap services can normally not be interrupted by standard or PEC interrupts.

Table 7 shows all possible exceptions or error conditions that can arise during runtime:

Table 7 Trap Summary

Exception Condition	Trap Flag	Trap Vector	Vector Location ¹⁾	Trap Number	Trap Priority
Reset Functions	–	RESET	xx'0000 _H	00 _H	III
Class A Hardware Traps:					
• System Request 0	SR0	SR0TRAP	xx'0008 _H	02 _H	II
• Stack Overflow	STKOF	STOTRAP	xx'0010 _H	04 _H	II
• Stack Underflow	STKUF	STUTRAP	xx'0018 _H	06 _H	II
• Software Break	SOFTBRK	SBRKTRAP	xx'0020 _H	08 _H	II
Class B Hardware Traps:					
• System Request 1	SR1	BTRAP	xx'0028 _H	0A _H	I
• Undefined Opcode	UNDOPC	BTRAP	xx'0028 _H	0A _H	I
• Memory Access Error	ACER	BTRAP	xx'0028 _H	0A _H	I
• Protected Instruction Fault	PRTFLT	BTRAP	xx'0028 _H	0A _H	I
• Illegal Word Operand Access	ILLOPA	BTRAP	xx'0028 _H	0A _H	I
Reserved	–	–	[2C _H - 3C _H]	[0B _H - 0F _H]	–
Software Traps:	–	–	Any	Any	Current
• TRAP Instruction			[xx'0000 _H - xx'01FC _H] in steps of 4 _H	[00 _H - 7F _H]	CPU Priority

1) Register VECSEG defines the segment where the vector table is located to.

Bitfield VECSC in register CPUCON1 defines the distance between two adjacent vectors. This table represents the default setting, with a distance of 4 (two words) between two vectors.

3.5 On-Chip Debug Support (OCDS)

The On-Chip Debug Support system built into the XE167 provides a broad range of debug and emulation features. User software running on the XE167 can be debugged within the target system environment.

The OCDS is controlled by an external debugging device via the debug interface. This consists of the JTAG port conforming to IEEE-1149. The debug interface can be completed with an optional break interface.

The debugger controls the OCDS with a set of dedicated registers accessible via the debug interface (JTAG). In addition the OCDS system can be controlled by the CPU, e.g. by a monitor program. An injection interface allows the execution of OCDS-generated instructions by the CPU.

Multiple breakpoints can be triggered by on-chip hardware, by software, or by an external trigger input. Single stepping is supported, as is the injection of arbitrary instructions and read/write access to the complete internal address space. A breakpoint trigger can be answered with a CPU halt, a monitor call, a data transfer, or/and the activation of an external signal.

Tracing data can be obtained via the debug interface, or via the external bus interface for increased performance.

The JTAG interface uses four interface signals, to communicate with external circuitry. The debug interface can be amended with two optional break lines.

3.6 Capture/Compare Unit (CAPCOM2)

The CAPCOM2 unit supports generation and control of timing sequences on up to 16 channels with a maximum resolution of one system clock cycle (eight cycles in staggered mode). The CAPCOM2 unit is typically used to handle high-speed I/O tasks such as pulse and waveform generation, pulse width modulation (PWM), digital to analog (D/A) conversion, software timing, or time recording with respect to external events.

Two 16-bit timers (T7/T8) with reload registers provide two independent time bases for the capture/compare register array.

The input clock for the timers is programmable to a number of prescaled values of the internal system clock. It may also be derived from an overflow/underflow of timer T6 in module GPT2. This provides a wide range for the timer period and resolution while allowing precise adjustments for application-specific requirements. An external count input for CAPCOM2 timer T7 allows event scheduling for the capture/compare registers with respect to external events.

The capture/compare register array contains 16 dual purpose capture/compare registers. Each may be individually allocated to either CAPCOM2 timer T7 or T8 and programmed for a capture or compare function.

Each register of the CAPCOM2 module has one port pin associated with it. This serves as an input pin to trigger the capture function or as an output pin to indicate the occurrence of a compare event.

Table 8 Compare Modes (CAPCOM2)

Compare Modes	Function
Mode 0	Interrupt-only compare mode; Several compare interrupts per timer period are possible
Mode 1	Pin toggles on each compare match; Several compare events per timer period are possible
Mode 2	Interrupt-only compare mode; Only one compare interrupt per timer period is generated
Mode 3	Pin set '1' on match; pin reset '0' on compare timer overflow; Only one compare event per timer period is generated
Double Register Mode	Two registers operate on one pin; Pin toggles on each compare match; Several compare events per timer period are possible
Single Event Mode	Generates single edges or pulses; Can be used with any compare mode

3.8 General Purpose Timer (GPT12E) Unit

The GPT12E unit is a very flexible multifunctional timer/counter structure which can be used for many different timing tasks such as event timing and counting, pulse width and duty cycle measurements, pulse generation, or pulse multiplication.

The GPT12E unit incorporates five 16-bit timers organized in two separate modules, GPT1 and GPT2. Each timer in each module may either operate independently in a number of different modes or be concatenated with another timer of the same module.

Each of the three timers T2, T3, T4 of **module GPT1** can be configured individually for one of four basic modes of operation: Timer, Gated Timer, Counter, and Incremental Interface Mode. In Timer Mode, the input clock for a timer is derived from the system clock and divided by a programmable prescaler. Counter Mode allows timer clocking in reference to external events.

Pulse width or duty cycle measurement is supported in Gated Timer Mode, where the operation of a timer is controlled by the 'gate' level on an external input pin. For these purposes each timer has one associated port pin (TxIN) which serves as a gate or clock input. The maximum resolution of the timers in module GPT1 is 4 system clock cycles.

The counting direction (up/down) for each timer can be programmed by software or altered dynamically by an external signal on a port pin (TxEUD), e.g. to facilitate position tracking.

In Incremental Interface Mode the GPT1 timers can be directly connected to the incremental position sensor signals A and B through their respective inputs TxIN and TxEUD. Direction and counting signals are internally derived from these two input signals, so that the contents of the respective timer Tx corresponds to the sensor position. The third position sensor signal TOP0 can be connected to an interrupt input.

Timer T3 has an output toggle latch (T3OTL) which changes its state on each timer overflow/underflow. The state of this latch may be output on pin T3OUT e.g. for time out monitoring of external hardware components. It may also be used internally to clock timers T2 and T4 for measuring long time periods with high resolution.

In addition to the basic operating modes, T2 and T4 may be configured as reload or capture register for timer T3. A timer used as capture or reload register is stopped. The contents of timer T3 is captured into T2 or T4 in response to a signal at the associated input pin (TxIN). Timer T3 is reloaded with the contents of T2 or T4, triggered either by an external signal or a selectable state transition of its toggle latch T3OTL. When both T2 and T4 are configured to alternately reload T3 on opposite state transitions of T3OTL with the low and high times of a PWM signal, this signal can be continuously generated without software intervention.

Functional Description

With its maximum resolution of 2 system clock cycles, the **GPT2 module** provides precise event control and time measurement. It includes two timers (T5, T6) and a capture/reload register (CAPREL). Both timers can be clocked with an input clock which is derived from the CPU clock via a programmable prescaler or with external signals. The counting direction (up/down) for each timer can be programmed by software or altered dynamically with an external signal on a port pin (TxEUD). Concatenation of the timers is supported with the output toggle latch (T6OTL) of timer T6, which changes its state on each timer overflow/underflow.

The state of this latch may be used to clock timer T5, and/or it may be output on pin T6OUT. The overflows/underflows of timer T6 can also be used to clock the CAPCOM2 timers and to initiate a reload from the CAPREL register.

The CAPREL register can capture the contents of timer T5 based on an external signal transition on the corresponding port pin (CAPIN); timer T5 may optionally be cleared after the capture procedure. This allows the XE167 to measure absolute time differences or to perform pulse multiplication without software overhead.

The capture trigger (timer T5 to CAPREL) can also be generated upon transitions of GPT1 timer T3 inputs T3IN and/or T3EUD. This is especially advantageous when T3 operates in Incremental Interface Mode.

4.2 DC Parameters

These parameters are static or average values that may be exceeded during switching transitions (e.g. output current).

The XE167 can operate within a wide supply voltage range from 3.0 V to 5.5 V. However, during operation this supply voltage must remain within 10 percent of the selected nominal supply voltage. It cannot vary across the full operating voltage range.

Because of the supply voltage restriction and because electrical behavior depends on the supply voltage, the parameters are specified separately for the upper and the lower voltage range.

During operation, the supply voltages may only change with a maximum speed of $dV/dt < 1 \text{ V/ms}$.

Leakage current is strongly dependent on the operating temperature and the voltage level at the respective pin. The maximum values in the following tables apply under worst case conditions, i.e. maximum temperature and an input level equal to the supply voltage.

The value for the leakage current in an application can be determined by using the respective leakage derating formula (see tables) with values from that application.

The pads of the XE167 are designed to operate in various driver modes. The DC parameter specifications refer to the current limits in [Table 13](#).

Table 13 Current Limits for Port Output Drivers

Port Output Driver Mode	Maximum Output Current (I_{OLmax} , $-I_{OHmax}$) ¹⁾		Nominal Output Current (I_{OLnom} , $-I_{OHnom}$)	
	$V_{DDP} \geq 4.5 \text{ V}$	$V_{DDP} < 4.5 \text{ V}$	$V_{DDP} \geq 4.5 \text{ V}$	$V_{DDP} < 4.5 \text{ V}$
Strong driver	10 mA	10 mA	2.5 mA	2.5 mA
Medium driver	4.0 mA	2.5 mA	1.0 mA	1.0 mA
Weak driver	0.5 mA	0.5 mA	0.1 mA	0.1 mA

1) An output current above $|I_{OXnom}|$ may be drawn from up to three pins at the same time.

For any group of 16 neighboring output pins, the total output current in each direction (ΣI_{OL} and $\Sigma -I_{OH}$) must remain below 50 mA.

4.2.2 DC Parameters for Lower Voltage Area

These parameters apply to the lower IO voltage range, $3.0\text{ V} \leq V_{DDP} \leq 4.5\text{ V}$.

Table 15 DC Characteristics for Lower Voltage Range
(Operating Conditions apply)¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input low voltage (all except XTAL1)	V_{IL} SR	-0.3	–	$0.3 \times V_{DDP}$	V	–
Input high voltage (all except XTAL1)	V_{IH} SR	$0.7 \times V_{DDP}$	–	$V_{DDP} + 0.3$	V	–
Input Hysteresis ²⁾	HYS CC	$0.07 \times V_{DDP}$	–	–	V	V_{DDP} in [V], Series resistance = $0\ \Omega$
Output low voltage	V_{OL} CC	–	–	1.0	V	$I_{OL} \leq I_{OLmax}$ ³⁾
Output low voltage	V_{OL} CC	–	–	0.4	V	$I_{OL} \leq I_{OLnom}$ ³⁾⁴⁾
Output high voltage ⁵⁾	V_{OH} CC	$V_{DDP} - 1.0$	–	–	V	$I_{OH} \geq I_{OHmax}$ ³⁾
Output high voltage ⁵⁾	V_{OH} CC	$V_{DDP} - 0.4$	–	–	V	$I_{OH} \geq I_{OHnom}$ ³⁾⁴⁾
Input leakage current (Port 5, Port 15) ⁶⁾	I_{OZ1} CC	–	± 10	± 200	nA	$0\text{ V} < V_{IN} < V_{DDP}$
Input leakage current (all other) ⁶⁾⁷⁾	I_{OZ2} CC	–	± 0.2	± 2.5	μA	$T_J \leq 110^\circ\text{C}$, $0.45\text{ V} < V_{IN}$ $< V_{DDP}$
Pull level keep current	I_{PLK}	–	–	± 10	μA	$V_{PIN} \geq V_{IH}$ (up) ⁸⁾ $V_{PIN} \leq V_{IL}$ (dn)
Pull level force current	I_{PLF}	± 150	–	–	μA	$V_{PIN} \leq V_{IL}$ (up) ⁸⁾ $V_{PIN} \geq V_{IH}$ (dn)
Pin capacitance ⁹⁾ (digital inputs/outputs)	C_{IO} CC	–	–	10	pF	

1) Keeping signal levels within the limits specified in this table ensures operation without overload conditions. For signal levels outside these specifications, also refer to the specification of the overload current I_{OV} .

2) Not subject to production test - verified by design/characterization. Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It cannot suppress switching due to external system noise under all conditions.

3) The maximum deliverable output current of a port driver depends on the selected output driver mode, see [Table 13, Current Limits for Port Output Drivers](#). The limit for pin groups must be respected.

Electrical Parameters

Sample time and conversion time of the XE167's A/D converters are programmable. The timing above can be calculated using [Table 19](#).

The limit values for f_{ADCI} must not be exceeded when selecting the prescaler value.

Table 19 A/D Converter Computation Table

GLOBCTR.5-0 (DIVA)	A/D Converter Analog Clock f_{ADCI}	INPCRx.7-0 (STC)	Sample Time t_s
000000 _B	f_{SYS}	00 _H	$t_{\text{ADCI}} \times 2$
000001 _B	$f_{\text{SYS}} / 2$	01 _H	$t_{\text{ADCI}} \times 3$
000010 _B	$f_{\text{SYS}} / 3$	02 _H	$t_{\text{ADCI}} \times 4$
:	$f_{\text{SYS}} / (\text{DIVA}+1)$:	$t_{\text{ADCI}} \times (\text{STC}+2)$
111110 _B	$f_{\text{SYS}} / 63$	FE _H	$t_{\text{ADCI}} \times 256$
111111 _B	$f_{\text{SYS}} / 64$	FF _H	$t_{\text{ADCI}} \times 257$

Converter Timing Example A:

Assumptions: $f_{\text{SYS}} = 80 \text{ MHz}$ (i.e. $t_{\text{SYS}} = 12.5 \text{ ns}$), $\text{DIVA} = 03_{\text{H}}$, $\text{STC} = 00_{\text{H}}$
 Analog clock $f_{\text{ADCI}} = f_{\text{SYS}} / 4 = 20 \text{ MHz}$, i.e. $t_{\text{ADCI}} = 50 \text{ ns}$
 Sample time $t_s = t_{\text{ADCI}} \times 2 = 100 \text{ ns}$

Conversion 10-bit:

$$t_{\text{C10}} = 13 \times t_{\text{ADCI}} + 2 \times t_{\text{SYS}} = 13 \times 50 \text{ ns} + 2 \times 12.5 \text{ ns} = 0.675 \mu\text{s}$$

Conversion 8-bit:

$$t_{\text{C8}} = 11 \times t_{\text{ADCI}} + 2 \times t_{\text{SYS}} = 11 \times 50 \text{ ns} + 2 \times 12.5 \text{ ns} = 0.575 \mu\text{s}$$

Converter Timing Example B:

Assumptions: $f_{\text{SYS}} = 40 \text{ MHz}$ (i.e. $t_{\text{SYS}} = 25 \text{ ns}$), $\text{DIVA} = 02_{\text{H}}$, $\text{STC} = 03_{\text{H}}$
 Analog clock $f_{\text{ADCI}} = f_{\text{SYS}} / 3 = 13.3 \text{ MHz}$, i.e. $t_{\text{ADCI}} = 75 \text{ ns}$
 Sample time $t_s = t_{\text{ADCI}} \times 5 = 375 \text{ ns}$

Conversion 10-bit:

$$t_{\text{C10}} = 16 \times t_{\text{ADCI}} + 2 \times t_{\text{SYS}} = 16 \times 75 \text{ ns} + 2 \times 25 \text{ ns} = 1.25 \mu\text{s}$$

Conversion 8-bit:

$$t_{\text{C8}} = 14 \times t_{\text{ADCI}} + 2 \times t_{\text{SYS}} = 14 \times 75 \text{ ns} + 2 \times 25 \text{ ns} = 1.10 \mu\text{s}$$

Table 21 Coding of Bitfields LEVxV in Register SWDCON0

Code	Default Voltage Level	Notes ¹⁾
0000 _B	2.9 V	
0001 _B	3.0 V	LEV1V: reset request
0010 _B	3.1 V	
0011 _B	3.2 V	
0100 _B	3.3 V	
0101 _B	3.4 V	
0110 _B	3.6 V	
0111 _B	4.0 V	
1000 _B	4.2 V	
1001 _B	4.5 V	LEV2V: no request
1010 _B	4.6 V	
1011 _B	4.7 V	
1100 _B	4.8 V	
1101 _B	4.9 V	
1110 _B	5.0 V	
1111 _B	5.5 V	

1) The indicated default levels are selected automatically after a power reset.

Table 22 Coding of Bitfields LEVxV in Registers PVCyCONz

Code	Default Voltage Level	Notes ¹⁾
000 _B	0.9 V	
001 _B	1.0 V	
010 _B	1.1 V	
011 _B	1.2 V	
100 _B	1.3 V	LEV1V: reset request
101 _B	1.4 V	LEV2V: interrupt request
110 _B	1.5 V	
111 _B	1.6 V	

1) The indicated default levels are selected automatically after a power reset.

Wakeup Clock

When wakeup operation is selected ($\text{SYSCON0.CLKSEL} = 00_{\text{B}}$), the system clock is derived from the low-frequency wakeup clock source:

$$f_{\text{SYS}} = f_{\text{WU}}$$

In this mode, a basic functionality can be maintained without requiring an external clock source and while minimizing the power consumption.

Selecting and Changing the Operating Frequency

When selecting a clock source and the clock generation method, the required parameters must be carefully written to the respective bitfields, to avoid unintended intermediate states.

Many applications change the frequency of the system clock (f_{SYS}) during operation in order to optimize system performance and power consumption. Changing the operating frequency also changes the switching currents, which influences the power supply.

To ensure proper operation of the on-chip EVRs while they generate the core voltage, the operating frequency shall only be changed in certain steps. This prevents overshoots and undershoots of the supply voltage.

To avoid the indicated problems, recommended sequences are provided which ensure the intended operation of the clock system interacting with the power system.

Please refer to the Programmer's Guide.

4.6.3 External Clock Input Parameters

These parameters specify the external clock generation for the XE167. The clock can be generated in two ways:

- By connecting a **crystal or ceramic resonator** to pins XTAL1/XTAL2.
- By supplying an **external clock signal**. This clock signal can be supplied either to pin XTAL1 (core voltage domain) or to pin CLKIN1 (IO voltage domain).

If connected to CLKIN1, the input signal must reach the defined input levels V_{IL} and V_{IH} . In connected to XTAL1, a minimum amplitude V_{AX1} (peak-to-peak voltage) is sufficient for the operation of the on-chip oscillator.

Note: The given clock timing parameters ($t_1 \dots t_4$) are only valid for an external clock input signal.

Table 26 External Clock Input Characteristics
(Operating Conditions apply)

Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input voltage range limits for signal on XTAL1	V_{IX1} SR	$-1.7 + V_{DDI}$	–	1.7	V	1)
Input voltage (amplitude) on XTAL1	V_{AX1} SR	$0.3 \times V_{DDI}$	–	–	V	Peak-to-peak voltage ²⁾
XTAL1 input current	I_{IL} CC	–	–	± 20	μA	$0 V < V_{IN} < V_{DDI}$
Oscillator frequency	f_{OSC} CC	4	–	40	MHz	Clock signal
		4	–	16	MHz	Crystal or Resonator
High time	t_1 SR	6	–	–	ns	
Low time	t_2 SR	6	–	–	ns	
Rise time	t_3 SR	–	8	8	ns	
Fall time	t_4 SR	–	8	8	ns	

1) Overload conditions must not occur on pin XTAL1.

2) The amplitude voltage V_{AX1} refers to the offset voltage V_{OFF} . This offset voltage must be stable during the operation and the resulting voltage peaks must remain within the limits defined by V_{IX1} .

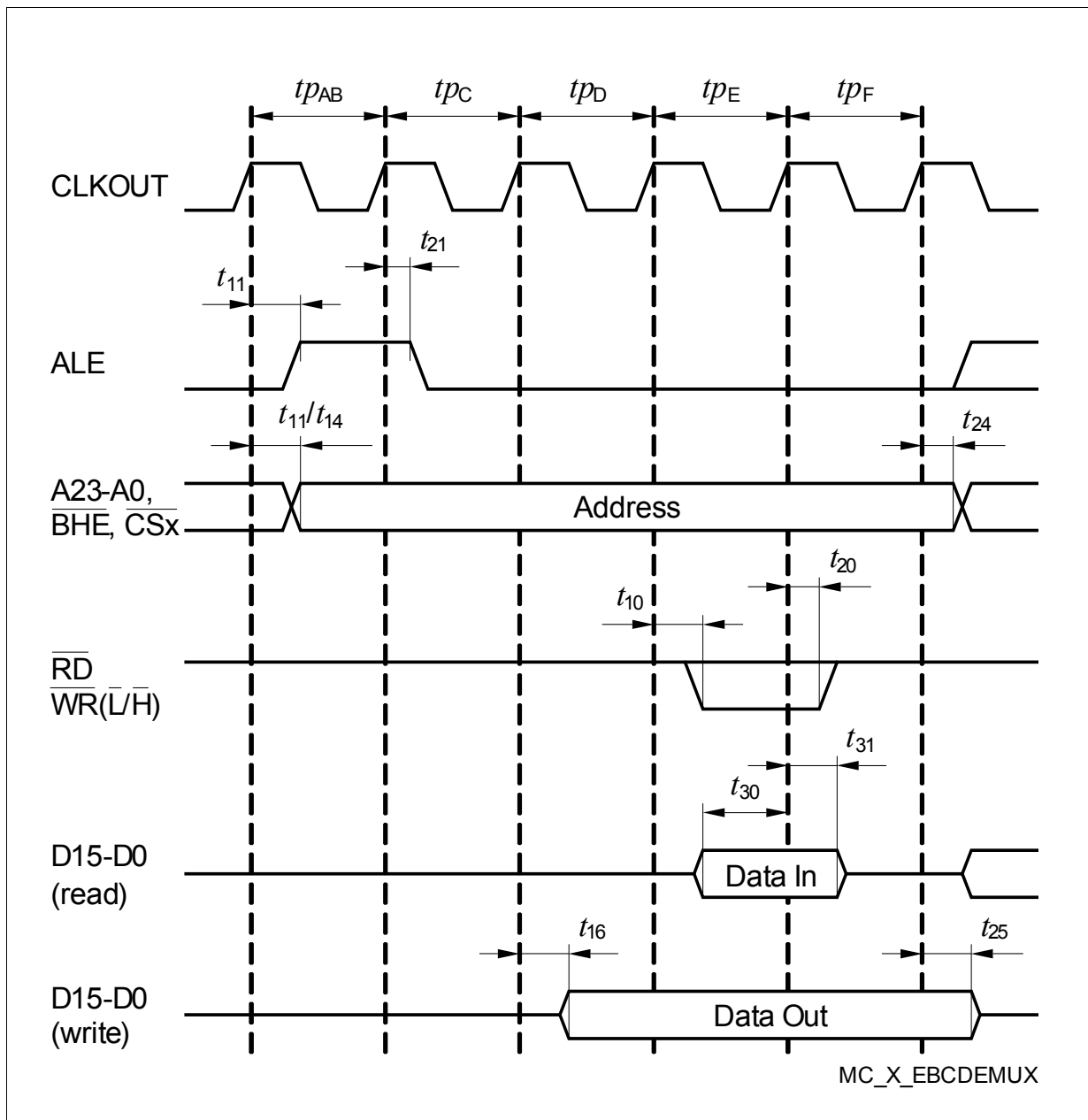
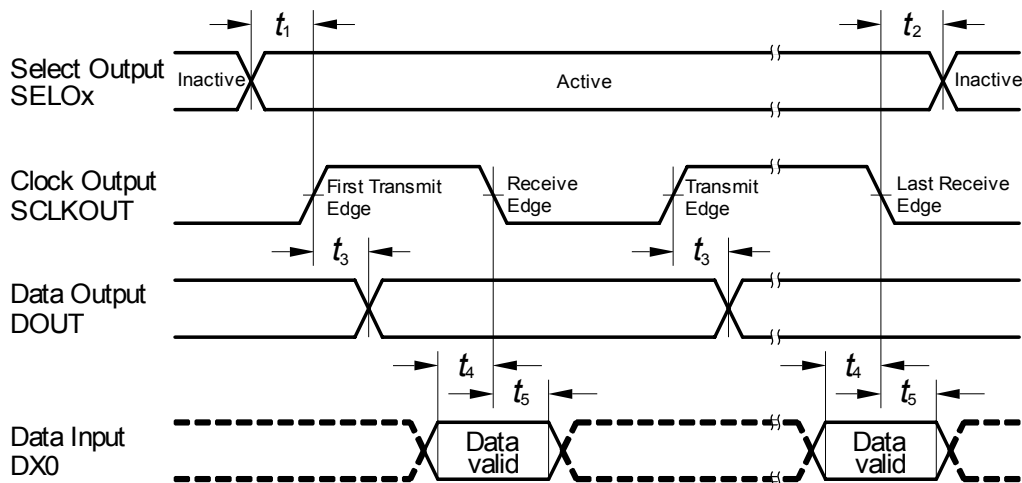
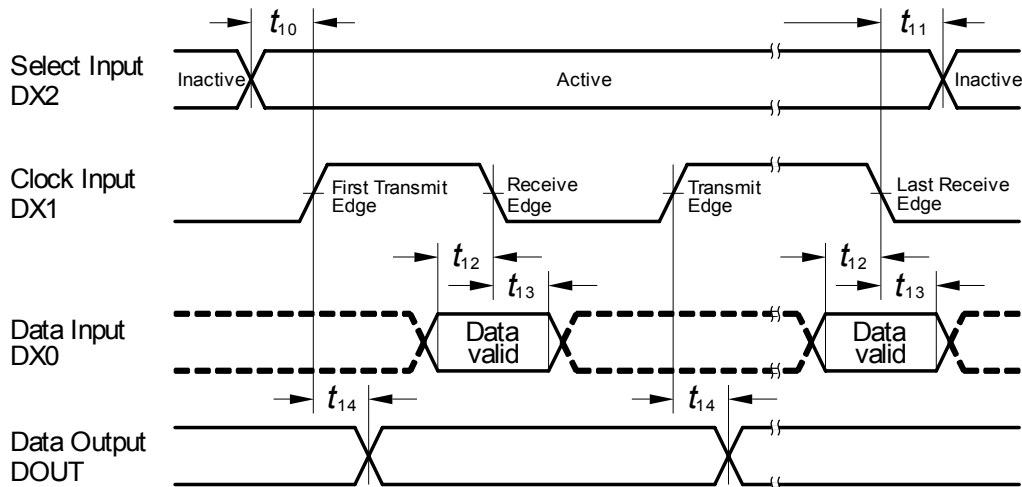


Figure 23 Demultiplexed Bus Cycle

Master Mode Timing



Slave Mode Timing



Transmit Edge: with this clock edge transmit data is shifted to transmit data output

Receive Edge: with this clock edge receive data at receive data input is latched

Drawn for BRGH.SCLKCFG = 00_B. Also valid for for SCLKCFG = 01_B with inverted SCLKOUT signal

USIC_SSC_TMGX.VSD

Figure 27 USIC - SSC Master/Slave Mode Timing

Note: This timing diagram shows a standard configuration where the slave select signal is low-active and the serial clock signal is not shifted and not inverted.